

Overview

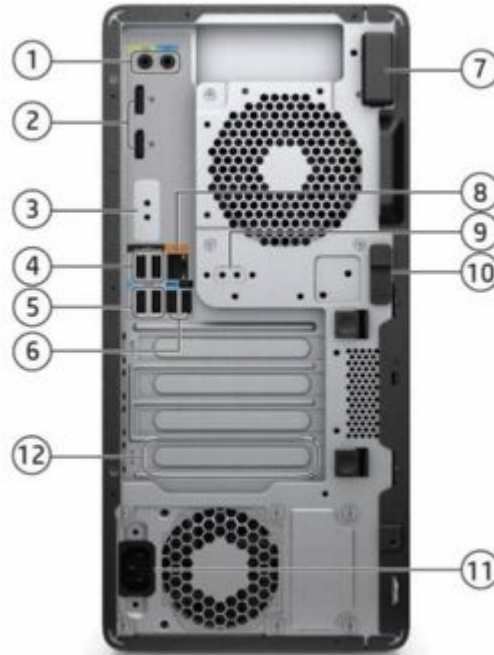
HP Z2 Tower G8 Workstation



front

1. HDD Activity LED
2. Power button
3. Universal audio jack (with CTIA & OMTP headset support)
4. (2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A)
5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
6. (1) Type-C® SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A)
7. SD card reader 4.0 (optional)
8. Slim ODD bay
9. External 5.25" bay

Overview



rear

- | | |
|--|--|
| <ol style="list-style-type: none"> 1. (1) Audio Line-in jack (1) Audio Line-out jack 2. (2) DisplayPort 1.4 3. Flex I/O module: choose one from the following: (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual Type-A SuperSpeed USB 5Gbps signaling rate port, (1) Type-C® SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode DisplayPort), (1) 2nd GbE LAN, (1) Thunderbolt 3 with Type-C® SuperSpeed USB4 40Gbps signaling rate* (cabled to PCIe AIC) 4. (2) Hi-Speed USB 480Mbps signaling rate port 5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port | <ol style="list-style-type: none"> 6. (1) Type-A SuperSpeed USB 5Gbps signaling rate port (1) Hi-Speed USB 480Mbps signaling rate port 7. WLAN Antenna (optional) 8. RJ-45 9. 2nd serial port (optional) 10. Release latch 11. Power connector 12. Type-C® Thunderbolt™ 3 port (optional) |
|--|--|

*Maximum speed requires DisplayPort™ and PCIe aggregation.

Note: All onboard Display support DP1.4/HBR2 when video output is via Intel Graphics.

Note: Flex I/O module Display support DP1.4/HBR3, resolution support up to 5120x3200 24bpp @60Hz

NOTE: TBT 3 will be available in Q3, 2021

Form Factor Tower

Operating Systems Preinstalled:

- Windows 10 Pro 64¹
- Windows 10 Pro 64 High End¹
- Windows 10 Pro 64 Workstation Plus¹
- Windows 10 Home 64 Plus¹
- Windows 10 Home 64 Advanced¹
- Linux®-ready²
- Ubuntu Linux 20.04 LTS³
- Red Hat® Enterprise Linux® (RHEL) Workstation - paper license (1 yr) only (not preinstalled)

Overview

Web-supported only:

- Windows 10 Enterprise 64¹

Supported Version:

- HP tested Windows 10, versions 1909, 2004, and 20H2 on this platform. For testing information on newer versions of Windows 10, please see: <https://support.hp.com/document/c05195282>.

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>. A full list of HP products and the Windows 10 versions tested is available on the support website. <https://support.hp.com/us-en/document/c05195282>

² For detailed Linux® OS/hardware information, see: http://www.hp.com/support/linux_hardware_matrix

³ Ubuntu Linux 20.04 LTS available Q3, 2021

Processors

| Name | Cores | Clock Speed (GHz) | Cache (MB) | Memory Speed (MT/s) | Hyper-Threading | Integrated Graphics | Intel® Turbo Boost Technology ³ | Featuring Intel® vPro® Technology ⁴ | 16GB Intel® Optane™ memory ² | TDP (W) |
|----------------------------------|-------|-------------------|------------|---------------------|-----------------|--------------------------|--|--|---|---------|
| Intel® Core™ i9 11900K Processor | 8 | 3.5 | 16 | 3200 | TRUE | Intel® UHD Graphics 750 | 5.2 | TRUE | Y | 125 |
| Intel® Core™ i9 11900F Processor | 8 | 2.5 | 16 | 3200 | TRUE | N/A | 5.1 | N/A | Y | 65 |
| Intel® Core™ i9 11900 Processor | 8 | 2.5 | 16 | 3200 | TRUE | Intel® UHD Graphics 750 | 5.1 | TRUE | Y | 65 |
| Intel® Core™ i7 11700K Processor | 8 | 3.6 | 16 | 3200 | TRUE | Intel® UHD Graphics 750 | 5 | TRUE | Y | 125 |
| Intel® Core™ i7 11700 processor | 8 | 2.5 | 16 | 3200 | TRUE | Intel® UHD Graphics 750 | 4.9 | TRUE | Y | 65 |
| Intel® Core™ i5 11600K processor | 6 | 3.9 | 12 | 3200 | TRUE | Intel® UHD Graphics 750 | 4.9 | TRUE | Y | 125 |
| Intel® Core™ i5 11600 processor | 6 | 2.8 | 12 | 3200 | TRUE | Intel® UHD Graphics 750 | 4.8 | TRUE | Y | 65 |
| Intel® Core™ i5 11500 processor | 6 | 2.7 | 12 | 3200 | TRUE | Intel® UHD Graphics 750 | 4.6 | TRUE | Y | 65 |
| Intel® Core™ i5 11400F processor | 6 | 2.6 | 12 | 3200 | TRUE | N/A | 4.4 | N/A | Y | 65 |
| Intel® Core™ i5 11400 processor | 6 | 2.6 | 12 | 3200 | TRUE | Intel® UHD Graphics 730 | 4.4 | N/A | Y | 65 |
| Intel® Xeon® W-1390P processor | 8 | 3.5 | 16 | 3200 | TRUE | Intel® UHD Graphics P750 | 5.2 | TRUE | Y | 125 |
| Intel® Xeon® W-1390 processor | 8 | 2.8 | 16 | 3200 | TRUE | Intel® UHD Graphics P750 | 5.1 | TRUE | Y | 80 |
| Intel® Xeon® W-1370P processor | 8 | 3.6 | 16 | 3200 | TRUE | Intel® UHD Graphics P750 | 5.2 | TRUE | Y | 125 |
| Intel® Xeon® W-1370 processor | 8 | 2.9 | 16 | 3200 | TRUE | Intel® UHD Graphics P750 | 5.1 | TRUE | Y | 80 |
| Intel® Xeon® W-1350P processor | 6 | 4 | 12 | 3200 | TRUE | Intel® UHD Graphics P750 | 5.1 | TRUE | Y | 125 |

Overview

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|-------------------------------|---|-----|----|------|------|--------------------------|---|------|---|----|
| Intel® Xeon® W-1350 processor | 6 | 3.3 | 12 | 3200 | TRUE | Intel® UHD Graphics P750 | 5 | TRUE | Y | 80 |
|-------------------------------|---|-----|----|------|------|--------------------------|---|------|---|----|

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.
3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information
4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

| | |
|--|---|
| Color | Black |
| Convertibility | No |
| Expansion Slots (see system board section for more details) | Slot 1: PCIe Gen4 x16 Slot 2: PCIe Gen3 x1 - with x4 Connector Slot 3: PCIe Gen3 x4 - with x16 Connector Slot 4: PCIe Gen3 x4 |
| Expansion Bays (see storage section for more details) | (2) Internal 3.5" bays (1) External 5.25" bay (1) Internal 2.5" bay (for SSD only) (1) Dedicated 9.5mm slim optical disk drive bay |
| Front I/O | (2) Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A), (2) Type-A SuperSpeed USB 10Gbps signaling rate port, (1) Type-C SuperSpeed® USB 20Gbps signaling rate port (charge supports up to 5V/3A, optional) , (1) SD card reader (optional), (1) universal audio jack |
| Internal I/O | (1) Hi-Speed USB 480Mbps signaling rate port (1) serial port |
| Rear I/O | (2) DisplayPort 1.4*, (1) Audio Line out, (1) Audio Line in, (1) RJ-45, (3) Hi-Speed USB 480Mbps signaling rate port, (2) Type-A SuperSpeed USB 10Gbps signaling rate port, (1) Type-A SuperSpeed USB 5Gbps signaling rate port, (1) serial (optional), (1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, Type-C® SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode DisplayPort), Dual Type -A SuperSpeed USB 5Gbps signaling rate port, 2nd 1GbE LAN, Thunderbolt 3** with SuperSpeed USB4 Type-C® 40Gbps signaling rate*** (cabled to PCIe AIC)) |

*All onboard Display support DP1.4/HBR2 when video output is via Intel Graphics.

**TBT 3 will be available in Q3, 2021

***Maximum speed requires DisplayPort™ and PCIe aggregation.

Overview

| | |
|---|--|
| Interfaces Supported | SD card reader (optional) |
| On-board RAID Support | RAID 0 RAID 1 |
| Chassis Dimensions (H x W x D) | H: 14" [356mm] W: 6.7" [169mm] D: 15.2" [385mm] |
| Packaged Dimensions | H: 20.39" (518mm) W: 11.61" (295mm) D: 19.29" (490mm) |
| Rack Dimensions | 5U |
| Weight | Exact weights depend upon configuration (System weight only). Starting at 7kg (15.43lbs.) |
| Temperature | Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr |
| Humidity | Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb |
| Maximum Altitude (non-pressurized)⁶ | Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Temperature for details. |
| Power Supply | 700W wide-ranging, active Power Factor Correction, 92% Efficiency. 500W wide-ranging, active Power Factor Correction, 90% Efficiency. 350W wide-ranging, active Power Factor Correction, 92% Efficiency. NOTE: The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links: 700W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2 500W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2 350W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2 |
| Backup Devices | For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup System offerings, please visit http://www.hp.com/go/connect |
| Chipset | Intel® W580 chipset |
| Memory | 4 DIMM slots, supporting up to 128GB ECC/non-ECC, and up to DDR4 3200 MT/s speed |

Supported Components

Processors

| | Factory Configured | Option Kit | Option Kit Part Number | Support Notes |
|---|--------------------|------------|------------------------|---------------|
| 11th Generation Intel® Core™ Processors* | | | | |
| Intel® Core™ i9 11900K Processor | Y | N | | |
| Intel® Core™ i9 11900F Processor | Y | N | | 1 |
| Intel® Core™ i9 11900 Processor | Y | N | | |
| Intel® Core™ i7 11700K Processor | Y | N | | |
| Intel® Core™ i7 11700 processor | Y | N | | |
| Intel® Core™ i5 11600K processor | Y | N | | |
| Intel® Core™ i5 11600 processor | Y | N | | |
| Intel® Core™ i5 11500 processor | Y | N | | |
| Intel® Core™ i5 11400F processor | Y | N | | 1 |
| Intel® Core™ i5 11400 processor | Y | N | | |
| Intel® Xeon® W Processors | | | | |
| Intel® Xeon® W-1390P processor | Y | N | | |
| Intel® Xeon® W-1390 processor | Y | N | | |
| Intel® Xeon® W-1370P processor | Y | N | | |
| Intel® Xeon® W-1370 processor | Y | N | | |
| Intel® Xeon® W-1350P processor | Y | N | | |
| Intel® Xeon® W-1350 processor | Y | N | | |

* These processors support only non-ECC memory

NOTE 1: No iGfx. A discrete graphics card must be purchased at the same time.

SATA Hard Drives

| | Factory Configured | Option Kit | Option Kit Part Number |
|---|--------------------|------------|------------------------|
| 500GB SATA 7200 rpm 6Gb/s 3.5" HDD | Y | Y | LQ036AA |
| 1TB SATA 7200 rpm 6Gb/s 3.5" HDD | Y | Y | LQ037AA |
| 2TB SATA 7200 rpm 6Gb/s 3.5" HDD | Y | | TBD |
| 1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Y | Y | W0R10AA |
| 2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Y | Y | 2Z274AA |
| 4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Y | Y | K4T76AA |
| 8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Y | Y | 2Z273AA |
| 500GB SATA 7.2K SED SFF HDD | Y | Y | D8N29AA |

Supported Components

PCIe Solid State Drives

| | | | |
|--|---|---|------------|
| HP ZTurbo PCIe-4X4 1TB TLC Z2 G8 TWR/SFF SSDKit | Y | Y | 201F5AA/AT |
| HP ZTurbo PCIe-4X4 256GB SED Z2 G8 TWR/SFF SSDKit | Y | Y | 201F6AA |
| HP ZTurbo PCIe-4X4 256GB TLC Z2 G8 TWR/SFF SSDKit | Y | Y | 201F7AA/AT |
| HP ZTurbo PCIe-4X4 2TB TLC Z2 G8 TWR/SFF SSDKit | Y | Y | 201F8AA |
| HP ZTurbo PCIe-4X4 512GB SED Z2 G8 TWR/SFF SSDKit | Y | Y | 201F9AA |
| HP ZTurbo PCIe-4X4 512GB TLC Z2 G8 TWR/SFF SSDKit | Y | Y | 201G0AA/AT |
| Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD | Y | Y | 223A3AA/AT |
| Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD | Y | Y | 223A4AA/AT |

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3 reserved for system recovery software.

Hard Drive Controllers

Factory Configured **Option Kit**

Integrated SATA Controller (Z2 G8)

Integrated SATA Controller, RAID 0,1 supported: 4x 6 Gb/s ports Y

Factory integrated RAID on motherboard for SATA drives

RAID 0 Data Configuration Y

RAID 1 Data Configuration Y

Factory integrated RAID on motherboard for Z Turbo Drive

RAID 0 Data Configuration Y

RAID 1 Data Configuration Y

NOTE: SATA hardware RAID is not supported on Linux® systems. The Linux® kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. All drives must be identical in type and capacity. Boot volume/RAID array must be less than 2 TB

NOTE: Requires identical drives (speeds, capacity, and interface).

NOTE: The HP Z2 Tower G8 Workstation is capable of configuring up to 2 Z Turbo Drives. By default, the Z Turbo Drive configured will be installed in the M.2 storage slot on the system's motherboard.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for system recovery software.

Supported Components

| Graphics | | Factory Configured | Option Kit | Option Kit Part Number | Supported # of cards |
|--------------------------------|--|--------------------|------------|------------------------|----------------------|
| Graphics Cable Adapters | HP DisplayPort To HDMI True 4k Adapter | Y | Y | 2JA63AA | |
| | HP Single miniDP-to-DP Adapter Cable | Y | Y | 2MY05AA | |
| | HP DisplayPort To DVI-D Adapter | Y | Y | FH973AA | |
| | HP DisplayPort To VGA Adapter | Y | Y | AS615AA | |
| | HP USB-C to DisplayPort Adapter | Y | Y | 4SH08AA | |
| | HP USB-C to HDMI Adapter | Y | Y | 4SH07AA | |
| | HP USB-C to VGA Adapter | Y | Y | 4SH06AA | |
| Entry 3D | NVIDIA® Quadro® P400 2GB Graphics | Y | Y | 1ME43AA/AT | 2 |
| Mid-range 3D | AMD Radeon™ Pro WX 3200 4GB Graphics | Y | Y | 6YT68AA/AT | 2 |
| | NVIDIA® T1000 4GB Graphics | Y | Y | 20X22AA/AT | 2 |
| High-End 3D | NVIDIA® RTX® A4000 16GB Graphics** | Y | Y | 20X24AA/AT | 1 |
| | AMD Radeon™ Pro W5500 8GB Graphics** | Y | Y | 9GC16AA/AT | 1 |
| | AMD Radeon™ Pro W5700 8GB Graphics** | Y | Y | 9GC15AA/AT | 1 |
| Ultra High-End 3D | NVIDIA® RTX® A5000 24GB Graphics* | Y | Y | 20X23AA/AT | 1 |

* Requires 750W chassis.

** Requires at least 500W chassis.

NOTE : NVIDIA® RTX A5000, NVIDIA® RTX A4000, NVIDIA® T1000 will be available in Q3, 2021

| Memory | | Factory Configured | Option Kit | Option Kit Part Number | Support Notes |
|--------|---------------------------------------|--------------------|------------|------------------------|---------------|
| | HP 4GB (1x4GB) DDR4-3200 nECC UDIMM | Y | Y | 141J1AA/AT | 2 |
| | HP 8GB (2x4GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 8GB (1x8GB) DDR4-3200 nECC UDIMM | Y | Y | 141J4AA/AT | 2 |
| | HP 8GB (1x8GB) DDR4-3200 ECC UDIMM | Y | Y | 141J3AA/AT | 1, 2 |
| | HP 16GB (2x8GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 16GB (2x8GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |
| | HP 16GB (1x16GB) DDR4-3200 nECC UDIMM | Y | Y | 141H3AA/AT | 2 |
| | HP 16GB (1x16GB) DDR4-3200 ECC UDIMM | Y | Y | 141H2AA/AT | 1, 2 |
| | HP 24GB (3x8GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 24GB (3x8GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |
| | HP 32GB (4x8GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 32GB (4x8GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |
| | HP 32GB (2x16GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 32GB (2x16GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |
| | HP 32GB (1x32GB) DDR4-3200 nECC UDIMM | Y | Y | 141H9AA/AT | 2 |
| | HP 32GB (1x32GB) DDR4-3200 ECC UDIMM | Y | Y | 141H7AA/AT | 1, 2 |
| | HP 64GB (4x16GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 64GB (4x16GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |
| | HP 64GB (2x32GB) DDR4-3200 nECC UDIMM | Y | N | | |
| | HP 64GB (2x32GB) DDR4-3200 ECC UDIMM | Y | N | | 1 |

Supported Components

| | | | |
|--|---|---|-----|
| HP 128GB (4x32GB) DDR4-3200 nECC UDIMM | Y | N | 3 |
| HP 128GB (4x32GB) DDR4-3200 ECC UDIMM | Y | N | 1,3 |

NOTES:

1. Intel® Xeon® can support either ECC or non-ECC memory; Intel® Core™ i5/i7/i9 processors only support non-ECC memory.
2. Two channels of DDR4 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.
3. Only 2933 MT/s speed can be achieved.

Note: When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Optical and Removable Storage

| | Factory Configured | Option Kit | Option Kit Part Number |
|--------------------------------------|--------------------|------------|------------------------|
| HP 9.5mm Slim DVD Writer | Y | N | |
| HP DX175 Removable HDD Frame/Carrier | Y | Y | 1ZX71AA |
| HP DX175 Removable HDD Spare Carrier | Y | Y | 1ZX72AA |
| HP SD card reader Z2 TWR | Y | Y | 141K3AA/AT |
| HP 9.5mm Slim DVD-ROM Drive | Y | N | |

NOTE: With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

| | Factory Configured | Option Kit | Option Kit Part Number |
|--|--------------------|------------|------------------------|
| Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 15.0) | Y | N | |
| HP 1GbE LAN Flex Port 2020 | Y | Y | 141J6AA/AT |
| Aquantia AQN108 1-Port 5GbE NIC | Y | Y | 1PM63AA |
| Intel Ethernet I350-T4 4-Port 1Gb NIC | N | Y | W8X25AA |
| Intel X550 10GBASE-T Dual Port NIC | Y | Y | 1QL46AA |
| Intel Ethernet Network Adapter I225-T1* | Y | Y | 406L9AA |
| Intel Ethernet I350-T2 2-Port 1Gb NIC | Y | Y | V4A91AA |
| Intel Wi-Fi 6 AX201 BT5 M.2 non-vPro | Y | N | |

*Planned to be available in Q3,2021

NOTE: The integrated network connection is required to support Intel® vPro® Technology.

NOTE: If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

NOTE: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not guarantee actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Supported Components

Input Devices

| | Factory Configured | Option Kit | Option Kit Part Number |
|--|--------------------|------------|------------------------|
| HP Premium Wireless Keyboard | Y | Y | Z9N41AA/AT |
| HP USB 320K Keyboard | Y | Y | 9SR37AA |
| HP USB Business Slim Wired SmartCard CCID Keyboard | Y | N | |
| HP PS/2 Business Slim Keyboard | N | Y | N3R86AA |
| HP USB Premium Wired Keyboard PROMO | Y | Y | Z9N40AT |
| HP 320M Wired Mouse | Y | Y | 9VA80AA |
| HP USB Premium Mouse | Y | Y | 1JR32AA |
| HP Wireless Premium Mouse | Y | Y | 1JR31AA |
| HP Promo PS/2 Mouse | N | Y | QY775AT |
| HP Wired Desktop 320MK Mouse and Keyboard | N | Y | 9SR36AA |

Other Hardware

| | Factory Configured | Option Kit | Option Kit Part Number |
|--|--------------------|------------|------------------------|
| HP Single TBT3 Type C and USB4 PCIe x4 Card ¹ | Y | Y | 3N3C1AA |
| HP Z2 Internal Serial Port and PS/2 Port | Y | Y | 141K9AA/AT |
| HP Z2 Power Cord Kit | Y | Y | 1N1D5AA |
| HP Z2 2nd serial port adapter | Y | Y | 141K8AA/AT |
| HP Z2 Tower Dust Filter | Y | Y | 141L2AA/AT |
| HP Z2 Tower Dust Filter and bezel | Y | Y | 141L3AA/AT |
| HP Z2 Internal Serial Port and PS/2 Port | Y | Y | 141K9AA/AT |
| HP PCIe x1 Parallel Port Card | Y | Y | N1M40AA |
| HP DP Flex Port 2020 | Y | Y | 141J7AA/AT |
| HP Dual USB-A 3.2 Gen1 Flex 2020 | Y | Y | 141J8AA/AT |
| HP Front Type-C SuperSpeed USB 20Gbps port | Y | Y | 201F4AA/AT |
| HP HDMI Flex Port 2020 | Y | Y | 141K1AA/AT |
| HP USB-C 3.2 Gen2 Alt Flex Port 2020 | Y | Y | 141K6AA/AT |
| HP VGA Flex Port 2020 | Y | Y | 141K7AA/AT |

¹Available in Q3, 2021

Racking and Physical Security

| | Factory Configured | Option Kit | Option Kit Part Number |
|--|--------------------|------------|------------------------|
| HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit | Y | Y | 2A8Y5AA |

Supported Components

| Software | Factory Configured | Option Kit | Support Notes |
|---|--------------------|------------|---------------|
| HP Performance Advisor | Y | N | 1 |
| HP PC Hardware Diagnostics UEFI (Windows OS only) | Y | N | 2 |
| HP PC Hardware Diagnostics Windows | Y | N | |
| ZCentral Remote Boost | Y | N | |
| HP Sure Sense | Y | N | |
| HP Notifications | Y | N | |
| HP Desktop Support Utility | Y | N | |
| HP Documentation | Y | N | |
| HP Image Assistant | N | N | |
| HP Support Assistant | N | N | |
| HP QuickDrop | Y | N | |
| myHP | Y | N | |

Notes:

1. Supports, and preinstalled with Windows 10 only. Also available as a free download from <http://www.hp.com/go/performanceadvisor>
2. Windows OS only

| Operating Systems |
|---|
| Windows 10 Pro 64 |
| Windows 10 Pro 64 High End |
| Windows 10 Pro 64 Workstation Plus |
| Windows 10 Home 64 Plus |
| Windows 10 Home 64 Advanced |
| Linux®-ready |
| Ubuntu Linux 20.04 LTS |
| Red Hat® Enterprise Linux® (RHEL) Workstation - paper license (1yr) only (not preinstalled) |

Notes: For detailed OS/hardware information for Linux, see: http://www.hp.com/support/linux_hardware_matrix

Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability - HP BIOS provides several technologies that help integrate the HP Z2 G8 Workstation into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates - Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability - HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- UEFI specification version 2.7
- Absolute Persistence agent - For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management - The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance - Industry leading acoustic emissions across the range of operating conditions.
- Serviceability - HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery - HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery

Additional HP BIOS Features:

- Power-On password - Helps prevent an unauthorized user from powering on the system.
- Administrator password - Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots
 - Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - USB charging ports

HP Sure Start Gen7 Start

- BIOS Integrity checking - Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS - Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled - System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

NOTE: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 11th generation processors.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen6¹

BIOS Update via Network

HP Secure Erase²

Absolute Persistence Module³

Pre-boot Authentication

HP Wake on WLAN

HP DriveLock & Automatic DriveLock

Supported Components

Software

- HP Support Assistant
- HP Image Assistant
- HP Desktop Support Utility
- HP Documentation
- HP Notifications
- HP PC Hardware Diagnostics UEFI
- HP PC Hardware Diagnostics Windows
- HP Performance Advisor⁴
- ZCentral Remote Boost⁵
- My HP
- HP QuickDrop

Manageability Features

- HP Driver Packs⁶
- HP System Software Manager (SSM)
- HP BIOS Config Utility (BCU)
- HP Manageability Integration Kit Gen4⁷
- HP Smart Support¹⁶

Client Security Software

- HP Client Security Manager Gen7⁸ including:
(including Credential Manager, HP Password Manager⁹, HP Spare Key)
- HP Power On Authentication
- Microsoft Defender¹⁰

Security Management

- HP Sure Click¹¹
- HP Sure Start Gen7¹²
- HP Sure Run Gen4¹³
- HP Sure Sense¹⁴
- HP Sure Recover Gen4¹⁵
- HP Pro Wolf Security

[1] HP BIOSphere Features may vary depending on the platform and configurations.

[2] HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

[3] Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

<http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

[4] HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one-and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>

[5] HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktops and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per device. Simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. Zcentral Remote Boost requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

[6] HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

[7] HP Manageability Integration Kit can be downloaded from <http://www8.hp.com/us/en/ads/clientmanagement/overview.html>

[8] HP Client Security Manager Gen6 requires Windows and is available on the select HP Elite and Pro PCs.

[10] Microsoft Defender Opt in and internet connection required for updates.

[11] HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

[12] HP Sure Start is available on select HP PCs and requires Windows 10.

[13] HP Sure Run is available on HP Workstation products equipped with 8th generation Intel® or AMD® processors.

[14] HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

Supported Components

[15] HP Sure Recover is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, and videos, etc. before using HP Sure Recover to avoid loss of data.

[16] HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Service or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

System Technical Specifications

System Board

| | |
|---|---|
| System Board Form Factor | Customized PCB 14.197x9.895 inch |
| Processor Socket | Single LGA-1200 |
| CPU Bus Speed | DMI |
| Chipset | Intel® PCH W580 |
| Super I/O Controller | Nuvoton SIO18 |
| Memory Expansion Slots | 4 DDR4 memory slots |
| Memory Type Supported | DDR4, UDIMM (Unbuffered), ECC& non-ECC |
| Memory Modes | Non-Interleaved for single channel. Interleaved when both channels are populated. |
| Memory Speed Supported | Up to 3200MT/s DDR4 |
| Memory Protection | ECC available on data |
| Maximum Memory | 128GB ¹ |
| Memory Configuration (Supported) | 4GB, 8GB, 16GB and 32GB non-ECC/8GB, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC and non-ECC memory DIMMs cannot be mixed in the same system |
| PCI Express Connectors | (1) PCI Express Gen4 slot x16 mechanical/ x16 electrical (full height, full length) (1) PCI Express Gen3 slot x4 mechanical/ x1 electrical (full height, full length, open-ended) (1) PCI Express Gen3 slot x16 mechanical/ x4 electrical (full height, full length) (1) PCI Express Gen3 slot x4 mechanical/ x4 electrical (full height, full length, open-ended) (1) M.2 2280 Storage (PCIe Gen4 x4) ² (1) M.2 2280 Storage (PCIe Gen3 x4) ² (1) M.2 2230 WLAN (PCIe Gen3 x1 + Intel CNVi) ² |

NOTE: The PCIe Gen 4 x16 slot is meant for HP qualified cards, configured or after market. HP does not provide warranty support for 3rd party cards.

Supported Drive Interfaces SATA

Integrated (4) Serial ATA interfaces (6Gb/s SATA). RAID 0 and 1 supported. Factory integrated RAID for Microsoft Windows only.

Integrated Graphics

Intel® UHD Graphics 730 (on Core i5-11400 processors); Intel® UHD Graphics 730 (on Core i5/i7/i9-11xxx processors); Intel® UHD Graphics P750 for Xeon processors
 Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display. Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel® UHD Graphics 730/750;
 Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display. Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel® UHD Graphics P750;
 3 DP 1.4 graphics ports integrated in motherboard; Supports up to three simultaneous displays across DisplayPort*/HDMI*/DVI output. Max. resolution supported on onboard DP 1.4/HBR2 ports: 4096x2304 @ 60Hz, 24bpp
 Max. resolution supported on flexIO DP 1.4/HBR3 ports: 5120x3200 @ 60Hz, 24bpp

Network Controller

Integrated Ethernet PHY Connection I219LM. Management capabilities: WOL, PXE 2.1 and AMT 15

Serial

Yes- requires optional Serial Port Adapter Kit

2nd Serial

Yes- requires optional Serial Port Adapter Kit

System Technical Specifications

| | | |
|--|-----------------|--|
| USB Connector(s) | Front | 2 Type-A SuperSpeed USB 5Gbps signaling rate port (1 charge port supports up to 5V/2.1A); 2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C® SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A) |
| | Rear | 3 High-speed USB 480Mbps signaling rate port; 1 Type-A SuperSpeed USB 5Gbps signaling rate port; 2 Type-A SuperSpeed USB 10Gbps signaling rate port; Flex I/O option: 1 Type-C® SuperSpeed USB 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual Type-A SuperSpeed USB 5Gbps signaling rate |
| | Internal | 1 High-speed USB 480Mbps signaling rate port |
| HD Integrated Audio | | Realtek ALC3205 |
| Flash ROM | | Yes |
| CPU Fan Header | | Yes |
| Memory Fan Header | | None |
| Chassis Fan Header | | 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header. |
| Front PCI Fan Header | | None |
| Front Control Panel/Speaker Header | | Yes |
| CMOS Battery Holder - Lithium | | Yes |
| Integrated Trusted Platform Module | | Integrated TPM 2.0 (Infineon SLB9670) Convertible to FIPS 140-2 Certified mode through firmware v7.85 The TPM module disabled where restricted by law, i.e. Russia. |
| Power Supply Headers | | Yes |
| Power Switch, Power LED & Hard Drive LED Header | | Yes |
| Clear Password Jumper | | None |
| Keyboard/Mouse | | USB or PS/2 (option) |
| Power Supply | | 700W EPA92, 500W EPA90 and 350W EPA92 |

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. Windows Operating Systems support up to 4 GB.

²M.2 storage supports compatible devices up to 80mm

PCIe Hold-down / Blower Kit Specification

Please refer to section Supported Components - Graphics for supported cards list.

System Technical Specifications

| Performance Class | Product Name | Slots space Required | Max Card Count | Number of Cards Require PCIe Hold-down / Blower Kit |
|--------------------------|-----------------------------|----------------------|----------------|---|
| Ultra High-End 3D | NVIDIA® RTX® A5000 24GB | 2 | 1 | 1 |
| High-End 3D | NVIDIA® RTX® A4000 16GB | 2 | 1 | 1 |
| | AMD Radeon™ Pro W5700 8GB | 2 | 1 | 1 |
| | AMD Radeon™ Pro W5500 8GB | 1 | 1 | 1 |
| Mid-range 3D | NVIDIA® T1000 4GB | 1 | 2 | 2 |
| | AMD Radeon™ Pro WX 3200 4GB | 1 | 2 | 2 |
| Entry | NVIDIA® Quadro® P400 2GB | 1 | 2 | 3 |

NOTE: The PCIe Hold-down / Blower Kit is automatically included when the 700W chassis is configured.

| System Configurations | | |
|---------------------------------|-----------------------------|--|
| Example Configuration #1 | Processor Info | Intel Core i5- 11400 2.60GHz 6C65W |
| | Memory Info | 8GB (1x 8GB) 3200 MHz DDR4 non-ECC |
| | Graphics Info | Intel® UHD Integrated Graphics 730 |
| | Disks/Optical/Floppy | 1x SATA 1TB 7.2k rpm / 1x 9.5mm Slim ODD |
| | PSU | 350W |
| | Other | |

| Energy Consumption (Watts) | | 115 VAC | | 230 VAC | | 100 VAC | |
|----------------------------|--------|------------------------|--------------|-------------|--------------|-------------|--------------|
| | | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| | | Windows long Idle (S0) | 18.98 | | 19.287 | | 19.175 |
| Windows short Idle (S0) | 20.713 | | 21.005 | | 20.917 | | |
| Windows Busy Typ (S0) | 95.045 | | 96.66 | | 96.118 | | |
| Windows Busy Max (S0) | 94.409 | | 93.629 | | 93.654 | | |
| Sleep (S3) | 0.887 | 0.83 | 0.968 | 0.853 | 0.963 | 0.923 | |
| Off (S5) | 0.645 | 0.604 | 0.674 | 0.567 | 0.655 | 0.615 | |
| Zero Power Mode (EuP) | 0.238 | | 0.298 | | 0.199 | | |

| Heat Dissipation (Btu/hr) | | 115 VAC | | 230 VAC | | 100 VAC | |
|---------------------------|------------|-------------------|--------------|-------------|--------------|-------------|--------------|
| | | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| | | Windows Idle (S0) | 64.75976 | | 65.807244 | | 65.4251 |
| Windows short Idle (S0) | 70.672756 | | 71.66906 | | 71.368804 | | |
| Windows Busy Typ (S0) | 324.29354 | | 329.80392 | | 327.954616 | | |
| Windows Busy Max (S0) | 322.123508 | | 319.462148 | | 319.547448 | | |
| Sleep (S3) | 3.026444 | 2.83196 | 3.302816 | 2.910436 | 3.285756 | 3.149276 | |
| Off (S5) | 2.20074 | 2.060848 | 2.299688 | 1.934604 | 2.23486 | 2.09838 | |
| Zero Power Mode (EuP) | 0.812056 | | 1.016776 | | 0.678988 | | |

System Technical Specifications

| | | |
|---------------------------------|-----------------------------|---------------------------------------|
| Example Configuration #2 | Processor Info | Intel Core i7- 11700 2.50GHz 8C65W |
| | Memory Info | 16GB (2x 8GB) 3200MHz DDR4 non-ECC |
| | Graphics Info | NVIDIA Quadro T1000 4 GB |
| | Disks/Optical/Floppy | 1x SATA 256GB SSD / 1x 9.5mm Slim ODD |
| | PSU | 500W |
| | Other | |

| | | | | | | | |
|-----------------------------------|-------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| Energy Consumption (Watts) | | 115 VAC | | 230 VAC | | 100 VAC | |
| | | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| | Windows long Idle (S0) | 23.49 | | 23.922 | | 23.695 | |
| | Windows short Idle (S0) | 25.186 | | 25.205 | | 24.933 | |
| | Windows Busy Typ (S0) | 137.849 | | 138.76 | | 134.09 | |
| | Windows Busy Max (S0) | 128.184 | | 129.18 | | 125.28 | |
| | Sleep (S3) | 0.994 | 0.95 | 0.963 | 0.853 | 0.878 | 0.824 |
| | Off (S5) | 0.737 | 0.706 | 0.646 | 0.572 | 0.74 | 0.703 |
| | Zero Power Mode (EuP) | 0.218 | | 0.299 | | 0.223 | |

| | | | | | | | |
|----------------------------------|-------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| Heat Dissipation (Btu/hr) | | 115 VAC | | 230 VAC | | 100 VAC | |
| | | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| | Windows Idle (S0) | 80.14788 | | 81.621864 | | 80.84734 | |
| | Windows short Idle (S0) | 85.934632 | | 85.99946 | | 85.071396 | |
| | Windows Busy Typ (S0) | 470.340788 | | 473.44912 | | 457.51508 | |
| | Windows Busy Max (S0) | 437.363808 | | 440.76216 | | 427.45536 | |
| | Sleep (S3) | 3.391528 | 3.2414 | 3.285756 | 2.910436 | 2.995736 | 2.811488 |
| | Off (S5) | 2.514644 | 2.408872 | 2.204152 | 1.951664 | 2.52488 | 2.398636 |
| | Zero Power Mode (EuP) | 0.743816 | | 1.020188 | | 0.760876 | |

| | | |
|---------------------------------|-----------------------------|--------------------------------------|
| Example Configuration #3 | Processor Info | Intel Core i9- 11900K 3.50GHz 8C125W |
| | Memory Info | 64GB (2x 32GB) 3200 MHz DDR4 ECC |
| | Graphics Info | NVIDIA GeForce RTX 3070 8 GB |
| | Disks/Optical/Floppy | 1x SATA 512GB SSD |
| | PSU | 700W |
| | Other | |

| | | | | | | | |
|-----------------------------------|-------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| Energy Consumption (Watts) | | 115 VAC | | 230 VAC | | 100 VAC | |
| | | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| | Windows long Idle (S0) | 26.2 | | 26.301 | | 26.251 | |
| | Windows short Idle (S0) | 27.866 | | 28.087 | | 27.588 | |
| | Windows Busy Typ (S0) | 232.415 | | 232.99 | | 230.363 | |
| | Windows Busy Max (S0) | 199.344 | | 200.99 | | 198.541 | |
| | Sleep (S3) | 1.009 | 0.973 | 1.025 | 0.862 | 0.951 | 0.913 |
| | Off (S5) | 0.599 | 0.553 | 0.651 | 0.524 | 0.565 | 0.507 |
| | Zero Power Mode (EuP) | 0.215 | | 0.294 | | 0.227 | |

System Technical Specifications

| Heat Dissipation (Btu/hr) | 115 VAC | | 230 VAC | | 100 VAC | |
|---------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| Windows Idle (S0) | 89.3944 | | 89.739012 | | 89.568412 | |
| Windows short Idle (S0) | 95.078792 | | 95.832844 | | 94.130256 | |
| Windows Busy Typ (S0) | 792.99998 | | 794.96188 | | 785.998556 | |
| Windows Busy Max (S0) | 680.161728 | | 685.77788 | | 677.421892 | |
| Sleep (S3) | 3.442708 | 3.319876 | 3.4973 | 2.941144 | 3.244812 | 3.115156 |
| Off (S5) | 2.043788 | 1.886836 | 2.221212 | 1.787888 | 1.92778 | 1.729884 |
| Zero Power Mode (EuP) | 0.73358 | | 1.003128 | | 0.774524 | |

| | | |
|---------------------------------|-----------------------------|-----------------------------------|
| Example Configuration #4 | Processor Info | Intel Xeon W- 1370P 3.60G 8C125W |
| | Memory Info | 128GB (4x 32GB) 3200 MHz DDR4 ECC |
| | Graphics Info | NVIDIA Quadro RTX A4000 16 GB |
| | Disks/Optical/Floppy | 1x SATA 1TB SSD Z Turbo |
| | PSU | 700W |
| | Other | |

| Energy Consumption (Watts) | 115 VAC | | 230 VAC | | 100 VAC | |
|----------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| Windows long Idle (S0) | TBD | | TBD | | TBD | |
| Windows short Idle (S0) | TBD | | TBD | | TBD | |
| Windows Busy Typ (S0) | TBD | | TBD | | TBD | |
| Windows Busy Max (S0) | TBD | | TBD | | TBD | |
| Sleep (S3) | TBD | TBD | TBD | TBD | TBD | TBD |
| Off (S5) | TBD | TBD | TBD | TBD | TBD | TBD |
| Zero Power Mode (EuP) | TBD | | TBD | | TBD | |

| Heat Dissipation (Btu/hr) | 115 VAC | | 230 VAC | | 100 VAC | |
|---------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| Windows Idle (S0) | TBD | | TBD | | TBD | |
| Windows short Idle (S0) | TBD | | TBD | | TBD | |
| Windows Busy Typ (S0) | TBD | | TBD | | TBD | |
| Windows Busy Max (S0) | TBD | | TBD | | TBD | |
| Sleep (S3) | TBD | TBD | TBD | TBD | TBD | TBD |
| Off (S5) | TBD | TBD | TBD | TBD | TBD | TBD |
| Zero Power Mode (EuP) | TBD | | TBD | | TBD | |

| | | |
|---------------------------------|-----------------------------|----------------------------------|
| Example Configuration #5 | Processor Info | Intel Xeon W- 1350 3.30GHz 6C80W |
| | Memory Info | 16GB (2x 8GB) 3200 MHz DDR4 ECC |
| | Graphics Info | NVIDIA Quadro RTX A5000 24 GB |
| | Disks/Optical/Floppy | 1x SATA 1TB SSD Z Turbo |
| | PSU | 700W |
| | Other | |

System Technical Specifications

| Energy Consumption (Watts) | 115 VAC | | 230 VAC | | 100 VAC | |
|----------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| Windows long Idle (S0) | TBD | | TBD | | TBD | |
| Windows short Idle (S0) | TBD | | TBD | | TBD | |
| Windows Busy Typ (S0) | TBD | | TBD | | TBD | |
| Windows Busy Max (S0) | TBD | | TBD | | TBD | |
| Sleep (S3) | TBD | TBD | TBD | TBD | TBD | TBD |
| Off (S5) | TBD | TBD | TBD | TBD | TBD | TBD |
| Zero Power Mode (EuP) | TBD | | TBD | | TBD | |

| Heat Dissipation (Btu/hr) | 115 VAC | | 230 VAC | | 100 VAC | |
|---------------------------|-------------|--------------|-------------|--------------|-------------|--------------|
| | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled | LAN Enabled | LAN Disabled |
| Windows Idle (S0) | TBD | | TBD | | TBD | |
| Windows short Idle (S0) | TBD | | TBD | | TBD | |
| Windows Busy Typ (S0) | TBD | | TBD | | TBD | |
| Windows Busy Max (S0) | TBD | | TBD | | TBD | |
| Sleep (S3) | TBD | TBD | TBD | TBD | TBD | TBD |
| Off (S5) | TBD | TBD | TBD | TBD | TBD | TBD |
| Zero Power Mode (EuP) | TBD | | TBD | | TBD | |

NOTE: The Power Supply Efficiency report may be found at the following links:

<https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2>

| | |
|---|---|
| Operating Voltage Range | 90-269 VAC |
| Rated Voltage Range | 100-240 VAC |
| Rated Line Frequency | 50-60 Hz |
| Operating Line Frequency Range | 47-66 Hz |
| Rated Input Current | 6A @ 100-240V |
| Heat Dissipation | Typical: 444 btu/hr (112 kcal/hr) Maximum: 1484 btu/hr (374 kcal/hr) |
| ENERGY STAR® certified (Config Dependent) | Yes |
| CECP Compliant @ 220V | Yes |
| FEMP Standby Power Compliant | Yes, with Wake-on-LAN disabled: <1W in S4/S5 - Power Off |
| Built-in Self Test (BIST) LED | Yes |
| Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V) | Yes |
| Hood Lock Header | Yes |
| ErP Lot 6- Tier 1 Compliance @ 230V (<1W in S5 - Power Off) | Yes |
| ErP Lot 6- Tier 2 Compliance @ 230V (<0.5W in S5 - Power Off) | Yes |

System Technical Specifications

| | | |
|--|-----------------------|--------------------------------------|
| Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor) | | |
| System Configuration (Entry level) | Processor Info | Intel® Core™ i9-11900 2.5 GHz 8C CPU |
| | Memory Info | 128GB DDR4-3200 nECC (4x32GB) RAM |
| | Graphics Info | Intel® UHD |
| | Disks/Optical | 1 TB SATA 6Gb/s SSD / No Optical / |
| | Power Supply | 700W PSU |

| Declared Noise Emissions | | Sound Power (LWAd, bels) | Deskside Sound Pressure (LpAm, decibels) |
|---------------------------------|--|---------------------------------|---|
| | Idle | 3.31 | 13.8 |
| | Hard drive Operating (random reads) | 3.4 | 15.7 |

| | | |
|---|-----------------------|---|
| System Configuration (Mid-level) | Processor Info | Intel® Xeon® processor W-1290 3.2 GHz 10C CPU |
| | Memory Info | 128GB DDR4-2933 ECC (4x32GB) RAM |
| | Graphics Info | NVIDIA® Quadro® RTX 5000 16GB |
| | Disks/Optical | 2 x 2TB SATA 7200 rpm 6Gb/s / No Optical |
| | Power Supply | 700W PSU |

| Declared Noise Emissions | | Sound Power (LWAd, bels) | Deskside Sound Pressure (LpAm, decibels) |
|---------------------------------|--|---------------------------------|---|
| | Idle | 3.55 | 18.4 |
| | Hard drive Operating (random reads) | 3.9 | 22.4 |

| | | |
|--|-----------------------|--|
| System Configuration (High-end) | Processor Info | Intel® Core™ i9-11900K 3.5GHz 8C CPU |
| | Memory Info | 128GB DDR4-2933 nECC (4x32GB) RAM |
| | Graphics Info | NVIDIA® Quadro® RTX 5000 16GB |
| | Disks/Optical | 2 x 2TB SATA 7200 rpm 6Gb/s / No Optical |
| | Power Supply | 700W PSU |

| Declared Noise Emissions | | Sound Power (LWAd, bels) | Deskside Sound Pressure (LpAm, decibels) |
|---------------------------------|--|---------------------------------|---|
| | Idle | 3.64 | 18.8 |
| | Hard drive Operating (random reads) | 3.85 | 20.8 |

System Technical Specifications

| | | |
|-----------------------------------|-------------------------|--|
| Environmental Requirements | Temperature | Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr |
| | Humidity | Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb |
| | Maximum Altitude | Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Cooling for details. |
| | Dynamic | Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g ² /Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g ² /Hz |
| | Cooling | Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation, up to 3048 m (10,000 feet) |

Physical Security and Serviceability

| | |
|--|--|
| Access Panel | Tool-less Includes system board and memory information |
| Optical Drive | Tool-less, except for Screw-In carrier |
| Hard Drives | Tool-less, except for 2.5" bay |
| Expansion Cards | Tool-less |
| Processor Socket | Tool-less, except for the processor heatsink |
| Blue User Touch Points | Yes, on tool-less internal chassis mechanisms |
| Color-coordinated Cables and Connectors | Yes |
| Memory | Tool-less |
| System Board | Screw-In |
| Padlock Support | Yes (optional): Locks side cover and secures chassis from theft 0.22-in diameter padlock loop at rear of system |
| Cable Lock Support | Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system |
| Universal Chassis Clamp Lock Support | Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable Threaded feature at rear of system |
| Solenoid Lock and Hood Sensor | Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensor Kit detects when the access panel has been removed. |
| Rear Port Control Cover | No |
| CPUs and Heatsinks | A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less |
| Internal Speaker | Yes |
| Power Supply Fans | 70mm x 70mm x 25mm 4-wire PWM (non-serviceable) |

System Technical Specifications

| | |
|-----------------------------------|---|
| Access Panel Key Lock | No |
| Integrated Chassis Handles | Rear Recessed Handle |
| Power Supply | Requires T15 Torx or flat blade screwdriver |
| PCI Card Retention | Yes, rear (all), middle (optional), front (full-length cards with extender) |

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free call and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/lookuptool>. Service levels and response times for HP Care Packs may vary depending on your geographic location.

BIOS

| | |
|---|--|
| BIOS 64-bit Services | BIOS supports 64-bit Operating systems only. |
| PCI 3.0 Support | Full BIOS support for PCI Express through industry standard interfaces. |
| ATAPI | ATAPI Removable Media Device BIOS Specification Version 1.0. |
| BBS | BIOS Boot Specification v1.01. |
| WMI Support | WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications. |
| BIOS Boot Spec 1.01+ | Provides more control over how and from what devices the workstation will boot. |
| BIOS Power On | Users can define a specific date and time for the system to power on. |
| ROM Based Computer Setup Utility (F10) | Review and customize system configuration settings controlled by the BIOS. |
| System/Emergency ROM | |
| Flash Recovery with Video | Recovers system BIOS in corrupted Flash ROM. |
| Replicated Setup | Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup). |
| SMBIOS | System Management BIOS 3.2, for system management information. |
| Boot Control | Disables the ability to boot from removable media on supported devices. |
| Memory Change Alert | Alerts management console if memory is removed or changed. |
| Thermal Alert | Monitors the temperature state within the chassis. Three modes: <ul style="list-style-type: none"> • NORMAL - normal temperature ranges. • ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. • SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs. |
| Remote ROM Flash | Provides secure, fail-safe ROM image management from a central network console. |

System Technical Specifications

| | |
|---|--|
| ACPI (Advanced Configuration and Power Management Interface) | Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.0 for full compatibility with 64-bit operating systems. |
| Ownership Tag | A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen. |
| Remote Wakeup/Remote Shutdown | System administrators can power on, restart, and power off a client computer from a remote location. |
| Instantly Available PC (Suspend to RAM - ACPI sleep state S3) | Allows for very low power consumption with quick resume time. |
| Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server) | Allows a new or existing system to boot over the network and download software, including the operating system. |
| ROM revision levels | Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information. |
| System board revision level | Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. |
| Start-up Diagnostics (Power-on Self-Test) | Assesses system health at boot time with selectable levels of testing. |
| Auto Setup when new hardware installed | System automatically detects addition of new hardware. |
| Keyboard-less Operation | The system can be booted without a keyboard. |
| Localized ROM Setup | Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings. |
| Asset Tag | The user or MIS to set a unique tag string in non-volatile memory. |
| Per-slot Control | Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. |
| Adaptive Cooling | Control parameters are set according to detected hardware configuration for optimal acoustics. |
| Pre-boot Diagnostics | (Pre-video) critical errors are reported via beeps and blinks on the power LED. |
| UEFI Specification Revision 2.7 | |
| ACPI | Advanced Configuration and Power Management Interface, Version 6.0 |
| ATA (IDE) | ATA Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b |
| CD Boot | "El Torito" Bootable CD-ROM Format Specification Version 1.0 |
| EDD | Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0 |
| EHCI | Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 |
| PCI | PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 |
| PCI Express | PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0 |
| PMM | POST Memory Manager Specification, Version 1.01 |
| SATA | Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0 |
| SPD | PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B |
| TPM | Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). Common Criteria EAL4+ certified. FIPS 140-2 Certification TCG TPM Certified products list: http://www.trustedcomputinggroup.org/certification/tpm-certified-products/ |

System Technical Specifications

| | |
|---------------|---|
| UHCI | Universal Host Controller Interface Design Guide, Revision 1.1 |
| USB | Universal Serial Bus Revision 1.1 Specification |
| | Universal Serial Bus Revision 2.0 Specification |
| | Universal Serial Bus Revision 3.1 Specification |
| SMBIOS | System Management BIOS Reference Specification, Version 3.2 |
| | External BIOS simulator found at: http://csrsml.itcs.hp.com/ |

Social and Environmental Responsibility

Eco-Label Certifications & Declarations This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT² Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.
- TCO or TCO Certified Edge
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- 44.35% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- 80 Plus® Gold/Platinum/Silver/Titanium power supplies available
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
- Recycled Plastic cushions

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Ultra-slim Desktop model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply and a Microsoft Windows® operating system.

Energy Consumption (in accordance with US ENERGY STAR® test method)

| | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
|------------------|--------------|--------------|--------------|
| Normal Operation | TBD | TBD | TBD |
| Sleep | TBD | TBD | TBD |
| Off | TBD | TBD | TBD |

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. Computers marked with the ENERGY STAR® logo are compliant with the applicable U.S. Environmental

System Technical Specifications

Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
|-------------------|--------------|--------------|--------------|
| Normal Operation | TBD | TBD | TBD |
| Sleep | TBD | TBD | TBD |
| Off | TBD | TBD | TBD |

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

| | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) |
|----------------------------------|--|---|
| Typically Configured - Idle | 3.1 | 23 |
| Fixed Disk - Random writes | 3.1 | 24 |
| Optical Drive - Sequential reads | 4.8 | 42 |

Longevity and Upgrading This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and components contained in the product may include:

- 6 USB ports
- 2 memory slots
- 1 Mini PCIe half-length slot
- 1 MXM 3.0 Type A - 35W slot
- 1 mSATA slot
- 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD)
- 1 5.25" external supporting optical drive

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

Mercury greater than 1ppm by weight

Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains x% post-consumer recycled plastic (by wt.) *according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.*
- This product is xx.x% recycle-able when properly disposed of at end of life.

System Technical Specifications

| | | | |
|----------------------------|------------------|-------------------------------------|-----|
| Packaging Materials | External: | PAPER/Corrugated | TBD |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | TBD |
| | | PLASTIC/Polyethylene low density | TBD |

The plastic packaging material contains at least xx% recycled content.

The corrugated paper packaging materials contains at least xx% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [HP RoHS position statement](#).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants - may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

System Technical Specifications

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>
and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.
- Plastic cushions are made from >90% recycled plastic.

Technical Specifications - Processors

| Name | Cores | Clock Speed (GHz) | Intel® Turbo Boost Technology ³ | Cache (MB) | Memory Speed (MT/s) | Hyper-Threading | Integrated Graphics | Featuring Intel® vPro® Technology ⁴ | 16GB Intel® Optane™ memory ² | TDP (W) |
|----------------------------------|-------|-------------------|--|------------|---------------------|-----------------|--------------------------|--|---|---------|
| Intel® Core™ i9 11900K Processor | 8 | 3.5 | 5.2 | 16 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 125 |
| Intel® Core™ i9 11900F Processor | 8 | 2.5 | 5.1 | 16 | 3200 | Y | N/A | N/A | Y | 65 |
| Intel® Core™ i9 11900 Processor | 8 | 2.5 | 5.1 | 16 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 65 |
| Intel® Core™ i7 11700K Processor | 8 | 3.6 | 5 | 16 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 125 |
| Intel® Core™ i7 11700 processor | 8 | 2.5 | 4.9 | 16 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 65 |
| Intel® Core™ i5 11600K processor | 6 | 3.9 | 4.9 | 12 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 125 |
| Intel® Core™ i5 11600 processor | 6 | 2.8 | 4.8 | 12 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 65 |
| Intel® Core™ i5 11500 processor | 6 | 2.7 | 4.6 | 12 | 3200 | Y | Intel® UHD Graphics 750 | Y | Y | 65 |
| Intel® Core™ i5 11400F processor | 6 | 2.6 | 4.4 | 12 | 3200 | Y | N/A | N/A | Y | 65 |
| Intel® Core™ i5 11400 processor | 6 | 2.6 | 4.4 | 12 | 3200 | Y | Intel® UHD Graphics 730 | N/A | Y | 65 |
| Intel® Xeon® W-1390P processor | 8 | 3.5 | 5.2 | 16 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 125 |
| Intel® Xeon® W-1390 processor | 8 | 2.8 | 5.1 | 16 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 80 |
| Intel® Xeon® W-1370P processor | 8 | 3.6 | 5.2 | 16 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 125 |
| Intel® Xeon® W-1370 processor | 8 | 2.9 | 5.1 | 16 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 80 |
| Intel® Xeon® W-1350P processor | 6 | 4 | 5.1 | 12 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 125 |
| Intel® Xeon® W-1350 processor | 6 | 3.3 | 5 | 12 | 3200 | Y | Intel® UHD Graphics P750 | Y | Y | 80 |

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.

3. The specifications shown in the Intel® Turbo Boost Technology column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.

4. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

Technical Specifications - Hard Drives

| | | | | | | |
|--|--|--|---|--------------------------------------|----------------|--|
| SATA Hard Drives for HP Workstations | 500GB SATA 7200 rpm 6Gb/s 3.5" HDD | Capacity | 500GB | | | |
| | | Protocol | SATA | | | |
| | | Form Factor | 3.5" | | | |
| | | Controller | AHCI | | | |
| | | Height | 1 in; 2.54 cm | | | |
| | | Width | | Media Diameter | 3.5 in; 8.9 cm | |
| | | | | Physical Size | 4 in; 10.17 cm | |
| | | Interface | Serial ATA (6.0Gb/s), NCQ enabled | | | |
| | | Synchronous Transfer Rate (Maximum) | Up to 600MB/s * | | | |
| | | Buffer | 32MB | | | |
| | | Seek Time (typical reads, includes controller overhead, including settling) | Single Track | 2 ms * | | |
| | | | Average | 11 ms * | | |
| | | | Full Stroke | 21 ms * | | |
| | | Rotational Speed | 7,200 rpm | | | |
| | | Logical Blocks | 976,773,168 | | | |
| | | Operating Temperature | 41° to 131° F (5° to 55° C) | | | |
| | | <i>*Actual performance may vary.</i> | | | | |
| | | NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software. | | | | |
| | | | 1TB SATA 7200 rpm 6Gb/s 3.5" HDD | Capacity | 1TB | |
| | | | | Protocol | SATA | |
| | Form Factor | 3.5" | | | | |
| | Controller | AHCI | | | | |
| | Height | 1 in; 2.54 cm | | | | |
| | Width | | | Media Diameter 3.5 in; 8.9 cm | | |
| | | | | Physical Size 4 in; 10.17 cm | | |
| | Interface | Serial ATA (6.0Gb/s), NCQ enabled | | | | |
| | Synchronous Transfer Rate (Maximum) | Up to 600 MB/s * | | | | |
| | Buffer | 64MB | | | | |
| | Seek Time (typical reads, includes controller overhead, including settling) | Single Track | | 2 ms * | | |
| | | Average | | 11 ms * | | |
| | | Full Stroke | | 21 ms * | | |
| | Rotational Speed | 7,200 rpm | | | | |
| | Logical Blocks | 1,953,525,168 | | | | |
| | Operating Temperature | 41° to 131° F (5° to 55° C) | | | | |
| <i>*Actual performance may vary.</i> | | | | | | |
| NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software. | | | | | | |

Technical Specifications - Hard Drives

| | | | |
|---|--|------------------------------------|----------------|
| 2TB SATA 7200 rpm 6Gb/s 3.5" HDD | Capacity | 2TB | |
| | Protocol | SATA | |
| | Form Factor | 3.5" | |
| | Controller | AHCI | |
| | Annualized Failure Rate (based on Rated POH) | <0.62% | |
| | Height | 1 in; 2.54 cm | |
| | Width | Media Diameter | 3.5 in; 8.9 cm |
| | | Physical Size | 4 in; 10.17 cm |
| | Interface | Serial ATA (6.0 Gb/s), NCQ Enabled | |
| | Synchronous Transfer Rate (Maximum) | Up to 600MB/s * | |
| | Buffer | 64MB | |
| | Seek Time (typical reads, includes controller overhead, including settling) | Single Track | 2.0 ms * |
| | | Average | 11 ms * |
| | | Full Stroke | 21 ms * |
| | Rotational Speed | 7,200 rpm | |
| | Logical Blocks | 3,907,029,168 | |
| Operating Temperature | 41° to 131° F (5° to 55° C) | | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|--|--|------------------------------------|----------------|
| 1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Capacity | 1TB | |
| | Height | 1 in; 2.54 cm | |
| | Protocol | SATA | |
| | Form Factor | 3.5" | |
| | Controller | AHCI | |
| | Reliability | 2.0M hours | |
| | Rated Power On Hours | 8760/yr | |
| | Annualized Failure Rate (based on Rated POH) | <0.62% | |
| | Width | Media Diameter | 3.5 in; 8.9 cm |
| | | Physical Size | 4 in; 10.17 cm |
| | Interface | Serial ATA (6.0 Gb/s), NCQ Enabled | |
| | Synchronous Transfer Rate (Maximum) | Up to 600MB/s * | |
| | Buffer | 128MB | |
| | Seek Time (typical reads, includes controller overhead, including settling) | Single Track | 0.32ms* |
| | | Average | 7.45ms* |
| | | Full Stroke | 14.2ms* |
| Rotational Speed | 7,200 rpm | | |
| Operating Temperature | 41° to 140° F (5° to 60° C) | | |
| Performance | Sequential Read | up to 226MB/s* | |
| | Sequential Write | up to 226MB/s* | |

Technical Specifications - Hard Drives

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|--|--|---------------------------------|----------------|
| 2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Capacity | 2TB | |
| | Protocol | SATA | |
| | Form Factor | 3.5" | |
| | Controller | AHCI | |
| | Reliability (MTBF) | 2.0M hours | |
| | Rated Power On Hours | 8760/yr | |
| | Annualized Failure Rate (based on Rated POH) | <0.62% | |
| | Rated for 24/7/365 Operation | | |
| | Physical Size (Height) | 1 in; 2.54 cm | |
| | Physical Size (Width) | 4 in; 10.17 cm | |
| | Media Diameter | 3.5 in; 8.9 cm | |
| | Interface | Serial ATA (6Gb/s), NCQ enabled | |
| | Synchronous Transfer Rate (Maximum) | Up to 600MB/s* | |
| | Buffer | 128MB | |
| | Seek Time (typical reads, includes controller overhead, including settling) | Single Track | 0.7ms* |
| | | Average | 8.5ms* |
| | | Full Stroke | 15.7ms* |
| | Rotational Speed | 7,200 rpm | |
| | Operating Temperature | 41° to 131° F (5° to 55° C) | |
| | Performance | Sequential Read | up to 226MB/s* |
| | | Sequential Write | up to 226MB/s* |

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

4TB SATA 7200 rpm
6Gb/s 3.5" HDD
(Enterprise Class)

| | | | | | | | |
|--|---|------------------------|----------------|-------------------------|----------------|--------------------|---------|
| Capacity | 4TB | | | | | | |
| Protocol | SATA | | | | | | |
| Form Factor | 3.5" | | | | | | |
| Controller | AHCI | | | | | | |
| Reliability | 2.0M hours | | | | | | |
| Rated Power On Hours | 8760/yr | | | | | | |
| Annualized Failure Rate (based on Rated POH) | <0.62% | | | | | | |
| Rated for 24/7/365 Operation | | | | | | | |
| Physical Size (Height) | 1 in; 2.54 cm | | | | | | |
| Physical Size (Width) | 4 in; 10.17 cm | | | | | | |
| Media Diameter | 3.5 in; 8.9 cm | | | | | | |
| Physical Size | 4 in; 10.17 cm | | | | | | |
| Interface | Serial ATA (6Gb/s), NCQ enabled | | | | | | |
| Synchronous Transfer Rate (Maximum) | Up to 600MB/s* | | | | | | |
| Buffer | 256MB | | | | | | |
| Seek Time (typical reads, includes controller overhead, including settling) | <table> <tr> <td>Single Track</td> <td>0.7ms*</td> </tr> <tr> <td>Average</td> <td>8.5ms*</td> </tr> <tr> <td>Full Stroke</td> <td>15.7ms*</td> </tr> </table> | Single Track | 0.7ms* | Average | 8.5ms* | Full Stroke | 15.7ms* |
| Single Track | 0.7ms* | | | | | | |
| Average | 8.5ms* | | | | | | |
| Full Stroke | 15.7ms* | | | | | | |
| Rotational Speed | 7,200 rpm | | | | | | |
| Operating Temperature | 41° to 131° F (5° to 55° C) | | | | | | |
| Performance | <table> <tr> <td>Sequential Read</td> <td>up to 226MB/s*</td> </tr> <tr> <td>Sequential Write</td> <td>up to 226MB/s*</td> </tr> </table> | Sequential Read | up to 226MB/s* | Sequential Write | up to 226MB/s* | | |
| Sequential Read | up to 226MB/s* | | | | | | |
| Sequential Write | up to 226MB/s* | | | | | | |
| Enterprise Class Features | High Reliability | | | | | | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | |
|--|---|-----------------------------------|----------------------------|
| 8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) | Capacity | 8TB | |
| | Protocol | SATA | |
| | Form Factor | 3.5" | |
| | Controller | AHCI | |
| | Reliability | 2.0M hours | |
| | Width | Media Diameter | 3.5 in; 8.9 cm |
| | | Physical Size | 4 in; 10.17 cm |
| | Interface | Serial ATA (6.0Gb/s), NCQ enabled | |
| | Synchronous Transfer Rate (Maximum) | Up to 600MB/s [1] | |
| | Buffer | 256MB | |
| | Seek Time (typical reads, includes controller overhead including settling) | Single Track | 0.7ms* |
| | | Average | 8.5ms* |
| | | Full Stroke | 15.7ms* |
| | Rotational Speed | 7,200 rpm | |
| | Operating Temperature | 41° to 140° F (5° to 60° C) | |
| | Performance | Sequential Read | up to 226MB/s ¹ |
| | | Sequential Write | up to 226MB/s ¹ |
| Enterprise Class Features | High Reliability | | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|-------------------------------------|---|-----------------------------------|------------------|
| 500GB SATA 7.2K SED 2.5" HDD | Capacity | 500GB | |
| | Protocol | SATA | |
| | Form Factor | 2.5" | |
| | Height | 0.275 in; 0.7 cm | |
| | Width | Media Diameter | 2.5 in; 6.36 cm |
| | | Physical Size | 2.75 in; 6.99 cm |
| | Interface | Serial ATA (6.0Gb/s), NCQ enabled | |
| | Synchronous Transfer Rate (Maximum) | Up to 600MB/s* | |
| | Buffer | 64MB | |
| | Seek Time (typical reads, includes controller overhead including settling) | Single Track | 1ms* |
| | | Average | 4.2ms* |
| | | Full Stroke | 25ms (Typical)* |
| | Rotational Speed | 7,200 rpm | |
| | Operating Temperature | 32° to 131° F (0° to 60° C) | |
| | Self-Encrypting Drive Support | Yes | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | | |
|--|------------------------------|-----------------------------------|------------|--|
| HP Z Turbo Drv PCIe-4X4 256GB TLC PCIe SSD (Z2G8) | Capacity | 256GB | | |
| | Protocol | PCIe | | |
| | Form Factor | M.2 in native Slot on motherboard | | |
| | Controller | NVMe | | |
| | NAND Type | 3D TLC | | |
| | Endurance | 75TBW (TB Written) | | |
| | Reliability | 1.5M Hours | | |
| | Interface | PCI Express 4.0 x4 electrical | | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | | |
| | Performance | Sequential Read | 5500MB/s* | |
| | | Sequential Write | 2300MB/s* | |
| | | Random Read | 400K IOPS* | |
| | | Random Write | 400K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | | |
|--|------------------------------|-----------------------------------|------------|--|
| HP Z Turbo Drv PCIe-4X4 512GB TLC PCIe SSD (Z2G8) | Capacity | 512GB | | |
| | Protocol | PCIe | | |
| | Form Factor | M.2 in native Slot on motherboard | | |
| | Controller | NVMe | | |
| | NAND Type | 3D TLC | | |
| | Endurance | 150TBW (TB Written) | | |
| | Reliability (MTBF) | 1.5M hours | | |
| | Interface | PCI Express 4.0 x4 electrical | | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | | |
| | Performance | Sequential Read | 6400MB/s* | |
| | | Sequential Write | 3400MB/s* | |
| | | Random Read | 600K IOPS* | |
| | | Random Write | 600K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | |
|--|------------------------------|-----------------------------------|-----------|
| HP Z Turbo Drv PCIe-4X4 1TB TLC PCIe SSD (Z2G8) | Capacity | 1TB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 300TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 6500MB/s* |
| | | Sequential Write | 5000MB/s* |
| | Random Read | 800K IOPS* | |
| | Random Write | 800K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|--|------------------------------|-----------------------------------|-----------|
| HP Z Turbo Drv PCIe-4X4 2TB TLC PCIe SSD (Z2G8) | Capacity | 2TB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 600TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 6500MB/s* |
| | | Sequential Write | 5000MB/s* |
| | Random Read | 800K IOPS* | |
| | Random Write | 800K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | |
|---|--------------------------------------|-----------------------------------|------------|
| HP Z Turbo Drv 256GB TLC PCIe SED OPAL2 (Z2G8) | Capacity | 256GB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 75TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 5500MB/s* |
| | | Sequential Write | 2300MB/s* |
| | | Random Read | 400K IOPS* |
| | | Random Write | 400K IOPS* |
| | Self-Encrypting Drive Support | OPAL2 | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|---|--------------------------------------|-----------------------------------|------------|
| HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G8) | Capacity | 512GB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 150TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 6400MB/s* |
| | | Sequential Write | 3400MB/s* |
| | | Random Read | 600K IOPS* |
| | | Random Write | 600K IOPS* |
| | Self-Encrypting Drive Support | OPAL2 | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | |
|---|--------------------------------------|-----------------------------------|------------|
| HP Z Turbo Drv 1TB TLC PCIe SED OPAL2 (Z2G8) | Capacity | 1TB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 300TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 6500MB/s* |
| | | Sequential Write | 5000MB/s* |
| | | Random Read | 800K IOPS* |
| | | Random Write | 800K IOPS* |
| | Self-Encrypting Drive Support | OPAL2 | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|---|--------------------------------------|-----------------------------------|------------|
| HP Z Turbo Drv 2TB TLC PCIe SED OPAL2 (Z2G8) | Capacity | 2TB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 600TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 4.0 x4 electrical | |
| | Operating Temperature | 32° to 178° F (0° to 81° C) | |
| | Performance | Sequential Read | 6500MB/s* |
| | | Sequential Write | 5000MB/s* |
| | | Random Read | 800K IOPS* |
| | | Random Write | 800K IOPS* |
| | Self-Encrypting Drive Support | OPAL2 | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | | | |
|---|------------------------------|-----------------------------------|-----------|
| 256GB M.2 2280 PCIe TLC SSD (Z2G8) | Capacity | 256GB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 200TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 3.0 x4 electrical | |
| | Operating Temperature | 32° to 158° F (0° to 70° C) | |
| | Performance | Sequential Read | 3100MB/s* |
| | | Sequential Write | 1400MB/s* |
| Random Read | | 200K IOPS* | |
| Random Write | | 400K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | | | |
|---|------------------------------|-----------------------------------|-----------|
| 512GB M.2 2280 PCIe TLC SSD (Z2G8) | Capacity | 512GB | |
| | Protocol | PCIe | |
| | Form Factor | M.2 in native Slot on motherboard | |
| | Controller | NVMe | |
| | NAND Type | 3D TLC | |
| | Endurance | 300TBW (TB Written) | |
| | Reliability | 1.5M Hours | |
| | Interface | PCI Express 3.0 x4 electrical | |
| | Operating Temperature | 32° to 158° F (0° to 70° C) | |
| | Performance | Sequential Read | 3400MB/s* |
| | | Sequential Write | 2500MB/s* |
| Random Read | | 380K IOPS* | |
| Random Write | | 430K IOPS* | |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Hard Drives

| | |
|--|-----------------------------------|
| 1TB M.2 2280 PCIe TLC SSD Capacity (Z2G8) | 1TB |
| Protocol | PCIe |
| Form Factor | M.2 in native Slot on motherboard |
| Controller | NVMe |
| NAND Type | 3D TLC |
| Endurance | 400TBW (TB Written) |
| Reliability | 1.5M Hours |
| Interface | PCI Express 4.0 x4 electrical |
| Operating Temperature | 32° to 158° F (0° to 70° C) |
| Performance | Sequential Read 3400MB/s* |
| | Sequential Write 2500MB/s* |
| | Random Read 500K IOPS* |
| | Random Write 440K IOPS* |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

| | |
|--|-----------------------------------|
| 2TB M.2 2280 PCIe TLC SSD Capacity (Z2G8) | 2TB |
| Protocol | PCIe |
| Form Factor | M.2 in native Slot on motherboard |
| Controller | NVMe |
| NAND Type | 3D TLC |
| Endurance | 600TBW (TB Written) |
| Reliability | 1.5M Hours |
| Interface | PCI Express 3.0 x4 electrical |
| Operating Temperature | 32° to 158° F (0° to 70° C) |
| Performance | Sequential Read 3400MB/s* |
| | Sequential Write 2500MB/s* |
| | Random Read 430K IOPS* |
| | Random Write 500K IOPS* |

*Actual performance may vary.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications - Graphics

| | | |
|---|-----------------------------------|--|
| Integrated Intel® UHD Graphics (Z2 G8) | Form Factor | Integrated in select Intel® Xeon®, Intel® Core™ i9/i7, and Intel® Core™ i5 processors. |
| | | Check specific platform specifications for selections. |
| | Graphics Controller | Intel® UHD Graphics |
| | Memory | Unified Memory Architecture (UMA) frame buffer. Graphics memory is shared with system memory. Size selectable between 64 MB to 1024 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel® DVMT 5.0), to provide an optimal balance between graphics and system memory use. |
| | Connectors | Check system platform specifications where Intel® UHD Graphics are available. |
| | Maximum Resolution | Display Port: 4096 x 2160 (5120x3200 could be achieved if output from FlexIO ports - DP/USB-C/TBT) HDMI: 4096 x 2160 DVI: 1920x1200 VGA: 2048x1536 |
| | | NOTE: For HDMI, DVI and VGA outputs, separate adapters may be required. |
| | Shading Architecture | Shader Model 6 compiler support |
| | Supported Graphics APIs | OpenGL 4.6 DirectX 12 |
| | Available Graphics Drivers | Windows 10 |

| | | |
|--|-----------------------------------|---|
| NVIDIA® Quadro® P400 2GB Graphics | Form Factor | Single Slot, Low Profile (2.713" H x 5.7" L) |
| | Graphics Controller | NVIDIA® Quadro® P400 Graphics Card Max Power: 30 Watts Cooling Solution: Active fan heatsink |
| | Bus Type | PCI Express 3.0 x16 |
| | Memory | Size: 2 GB GDDR5 |
| | Maximum Resolution | DisplayPort™ 1.4: - up to 3x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST) |
| | Display Output | 3 mDP (Mini DisplayPort™) 1.4 Connectors |
| | Shading Architecture | Full Microsoft DirectX 12 Shader Model 5.1 |
| | Supported Graphics APIs | OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA, OpenCL 1.x |
| | Available Graphics Drivers | Microsoft Windows 10 64-bit Linux® 64-bit (selected Enterprise distributions) |
| | | HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html |
| | Notes | *P400 only have mini-DisplayPort™ (mDP) video ports. Note : AMO kits for P400 Adapters |

Technical Specifications - Graphics

- Two mDP-to-DP Adapters are included in the P400 AMO kits.
- If more mDP-to-DP Adapters are needed, Adapters can be ordered separately:
 - 2MY05AA - HP Single miniDP-to-DP Adapter Cable

AMD Radeon™ Pro WX 3200 Form Factor 4GB Graphics

Graphics Controller

Low-Profile Single Slot (2.75 "H x 6.6"? L)

Radeon™ Pro WX 3200

Power: 56 Watts

Cooling Solution: Active fan heatsink

Memory

4GB GDDR5 memory

Maximum Resolution

DisplayPort™ 1.4:

- up to 4x 4096 x 2160 x 24 bpp @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

Full Microsoft DirectX 12 Shader Model 5.1

Display Outputs

4 mDP (Mini DisplayPort™) 1.4 Connectors

Supported Graphics APIs

DirectX® 12

OpenGL® 4.6

OpenCL™ 2.0

Vulkan™ 1.0

Available Graphics Drivers

Windows 10 64-bit

(Windows® 7 64-bit available from AMD)

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support Web site <http://welcome.hp.com/country/us/en/support.html>

Notes

1. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
2. WX 3200 only has mini-DisplayPort™ (mDP) video ports. Two mDP-to-DP Adapters are included in the WX 3200 AMO kit. If more mDP-to-DP Adapters are needed, Adapters can be ordered separately:

- 2MY05AA HP Single miniDP-to-DP Adapter Cable

Technical Specifications - Graphics

| | | |
|---|-----------------------------------|--|
| AMD Radeon™ Pro W5500 8GB Graphics | Form Factor | Single slot, full-height, 9.5" length |
| | Graphics Controller | Radeon™ Pro W5500 Power: 120 Watts Cooling Solution: Active Fan Heatsink |
| | Memory | 8GB GDDR6 |
| | Maximum Resolution | DisplayPort™ 1.4: - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST) |
| | Display Outputs | DisplayPort™ 1.4 Connectors FreeSync support |
| | Shading Architecture | Full Microsoft DirectX 12 Shader Model 5.1 |
| | Supported Graphics APIs | DirectX® 12 (12_1) OpenGL® 4.6 OpenCL™ 2.0 Vulkan™ 1.1 |
| | Available Graphics Drivers | Windows 10 64-bit Linux® 64-bit (selected Enterprise distributions) |

HP qualified drivers may be preloaded or available from the HP support Web site <http://welcome.hp.com/country/us/en/support.html>

| | | |
|-----------------------------------|-----------------------------------|--|
| NVIDIA® T1000 4GB Graphics | Form Factor | Low-Profile Single Slot (6.13" Length) |
| | Graphics Controller | NVIDIA® T1000 4GB Graphics Power: 50 Watts Cooling: Active Fan Heatsink |
| | Memory | 4GB GDDR6 memory |
| | Maximum Resolution | DisplayPort™ 1.4a: - up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed - 7680 x 4320 x 36 bpp @ 60Hz, compressed - supports Multi-Stream Transport (MST) |
| | Display Output | 4 mDP (Mini DisplayPort™) 1.4 Connectors |
| | Shading Architecture | Shader Model 5.1 |
| | Supported Graphics APIs | DirectX® 12.1 OpenGL® 4.6 OpenCL™ 1.2 Vulkan™ 1.2 |
| | Available Graphics Drivers | Windows 10 64-bit Linux® 64-bit (selected Enterprise distributions) |

HP qualified drivers may be preloaded or available from the HP support Web site <http://welcome.hp.com/country/us/en/support.html>

Technical Specifications - Graphics

**AMD Radeon™ Pro W5700
8GB Graphics**

**Form Factor
Graphics Controller**

Full-Height Dual Slot (10.5" Length)

Radeon™ Pro W5700

Power: 210 Watts

Cooling Solution: Active Fan Heatsink

Memory

8GB GDDR6

Maximum Resolution

DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz

- supports Multi-Stream Transport (MST)

Display Output

4 DisplayPort™ 1.4 Outputs

FreeSync support

Supported Graphics APIs

DirectX® 12 (12_1)

OpenGL® 4.6

OpenCL™ 2.0

Vulkan™ 1.0

Available Graphics Drivers

Windows 10 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support Web site:

<http://welcome.hp.com/country/us/en/support.html>

Technical Specifications - Optical and Removable Storage

| | | | |
|---|---|---|---|
| HP 9.5mm Slim DVD Writer | Description | 9.5mm height, tray-load | |
| | Mounting Orientation | Either horizontal or vertical | |
| | Interface Type | SATA/ATAPI | |
| | Dimensions (WxHxD) | 128 x 9.5 x 127mm | |
| | Supported Media Types | DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW | |
| | Disc Capacity | DVD-ROM 8.5 GB DL or 4.7 GB standard | |
| | Access Times | Full Stroke DVD | < 200 ms (seek) |
| | | Full Stroke CD | < 200 ms (seek) |
| | Maximum Data Transfer Rates | CD ROM Read | CD-ROM, CD-R Up to 24X CD-RW Up to 24X |
| | | DVD ROM Read | DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X |
| Power | Source | SATA DC power receptacle | |
| | DC Power Requirements | 5 VDC ± 5%-100 mV ripple p-p | |
| | DC Current | 5 VDC -< 800 mA typical, <1600 mA maximum | |
| Operating Environmental (all conditions non-condensing) | Temperature | 41° to 122° F (5° to 50° C) | |
| | Relative Humidity | 10% to 80% | |
| | Maximum Wet Bulb Temperature | 84° F (29° C) | |
| Operating Systems Supported | Windows 10, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000. Linux®. | | |
| Kit Contents | HP SATA DVD Writer drive, installation guide. | | |
| Approvals | USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUVT | | |

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Technical Specifications - Optical and Removable Storage

| | | | |
|-------------------------------------|--|--|---|
| HP 9.5mm Slim DVD-ROM Drive | Description | 9.5mm height, tray-load | |
| | Mounting Orientation | Either horizontal or vertical | |
| | Interface Type | SATA / ATAPI | |
| | Dimensions (WxHxD) | 128 x 9.5 x 127mm | |
| | Disc Capacity | DVD-ROM Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB | |
| | Access Times | DVD-ROM Single Layer | < 110 ms (typical) |
| | | CD-ROM Mode 1 | < 110 ms (typical) |
| | | Full Stroke DVD | < 230 ms (typical) |
| | | Full Stroke CD | < 220 ms (typical) |
| | Power | Source | SATA DC power receptacle |
| | | DC Power Requirements | 5 VDC ± 5%-100 mV ripple p-p |
| | | DC Current | 5 VDC - <800mA typical, < 1600 mA maximum |
| | Operating Environmental (all conditions non-condensing) | Temperature | 41° to 122° F (5° to 50° C) |
| Relative Humidity | | 10% to 80% | |
| Maximum Wet Bulb Temperature | | 84° F (29° C) | |
| Operating Systems Supported | Windows 10, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000. Linux®. | | |
| | Kit Contents | 9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation guide | |
| Approvals | USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUVT | | |

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Technical Specifications - Controller Cards

| | | |
|---|--|--|
| HP Thunderbolt™ 3/USB4 PCIe 3-Single-port I/O Card | Data Transfer Rate | Supports up to 40 Gb/s* 40,000 Mb/s) |
| | Devices Supported | Thunderbolt™ certified devices |
| | Bus Type | PCIe card, full height PCIe slot |
| | Ports | One USB4 Type-C® connector (Rear) |
| | Internal Connectors | Two wire-to-board-connectors |
| | System Requirements | Windows 10 64-bit, Intel® i5 series or higher processor, available on PCIe slot4. |
| | Temperature - Operating | 50° to 131° F (10° to 55° C) |
| | Temperature - Storage | -22° to 140° F (-30° to 60° C) |
| | Relative Humidity - Operating | 20% to 80% |
| | Compliances | FCC Part 15B, cULus, CE Mark EN55032B/EN55024, Taiwan BSMI, Korea KCC |
| | Operating Systems Supported | Windows 10 64-bit. |
| | Kit Contents | HP Thunderbolt™ 3/USB4 PCIe 3 Single-port I/O Card, Flex IO wire-to-board module, One full height and One Low-Profile brackets, One power cable, One DisplayPort™ and GPIO (General-Purpose Input/Output) cable, Installation documentation and warranty card. |

*Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

| | | |
|---|--------------------------------|--|
| Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 15.0) | Connector | RJ-45 |
| | Cabling | Twin Axial Cabling up to 10m |
| | Controller | Intel® I219LM GbE platform LAN connect networking controller |
| | Memory | 3 KB Tx and 3KB Rx FIFO packet buffer memory |
| | Data Rates Supported | 10/100/1000 Mbps |
| | Compliance | 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z |
| | Bus Architecture | PCI Express and SMBus |
| | Data Transfer Mode | PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state) |
| | Power Requirement | Requires 3.3V (integrated regulators for core Vdc) |
| | Boot ROM Support | Yes |
| | Network Transfer Mode | Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver) |
| | Network Transfer Rate | 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 10 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps |
| | Management Capabilities | vPro®, WOL, auto MDI crossover, PXE, Multi-port teaming, RSS, ACPI, Advanced cable diagnostic, loopback modes, AMT 15.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD) |

| | | |
|-----------------------------------|------------------------------|--|
| HP 1-Port 1GbE Flex IO NIC | Connector | RJ-45 |
| | Cabling | 1GbE over Category 5e (or better) up to 100m |
| | Controller | Realtek RTL8153 |
| | Data Rates Supported | 10/100/1000 Mbps |
| | Compliance | 802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.3az (Energy Efficient Ethernet) |
| | Bus Architecture | USB |
| | Power Requirement | Requires 3.3V (integrated regulators for core Vdc) |
| | Boot ROM Support | Yes |
| | Network Transfer Mode | Full-duplex; Half-duplex |
| | Network Transfer Rate | 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 10 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 100 Mbps 1000BASE-T (full-duplex) 1000 Mbps |
| | Operating Temperature | 32° to 131° F (0° to 55° C) |
| | Dimensions (HxW) | 1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm) |

Technical Specifications - Networking and Communications

Operating System Driver Support Windows 10 64-bit
Linux®

HP 10GbE SFP+ SR Transceiver

Operating Temperature 32°F to 113°F (0°C to 45°C)
Operating Humidity 0% to 85%, noncondensing
Dimensions (HxWxD) 0.47 x 0.54 x 2.19 inches
Kit Contents HP 10GbE SFP+ SR Transceiver

Intel® X550-T2 2-Port 10GbE NIC

Connector 2 RJ-45
Cabling 10GbE: Cat6a (or better) up to 100m
5GbE and below: Cat5e (or better) up to 100m
Controller Intel® Ethernet Controller X550
Network Transfer Rates Supported 10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE
Data Path Width PCIe Gen3x4
Power Requirement 11.2W (typical)
Operating Temperature 32° to 131° F (0° to 55° C)
Dimensions (HxW) 5.1 x 2.7 in (without brackets)
Operating System Driver Support Windows 10 64-bit
Linux®
Kit Contents

- Intel® X550-T2 2-Port 10GbE NIC with standard height bracket attached
- Low-profile bracket
- Product Literature

Aquantia® AQN-108 1-Port 5GbE NIC

Connector 1 RJ-45
Cabling Cat5e (or better) up to 100m
Controller Aquantia® AQN108
Network Transfer Rates Supported 5Gbe, 2.5GbE, 1GbE, 100MbE
Data Path Width PCIe Gen3x1
Power Requirement 3.5W (typical)
Operating Temperature 32° to 131° F (0° to 55° C)
Dimensions (HxW) 3.72 x 3.18 inches (without brackets)
Operating System Driver Support Windows 10 64-bit
Linux®
Kit Contents

- Aquantia AQN-108 1-Port 5GbE NIC with standard height bracket attached
- Low-profile bracket
- Product Literature

Technical Specifications - Networking and Communications

| | | |
|---------------------------------------|---|---|
| Intel® I350-T2 2-Port 1GbE NIC | Connector | 2 RJ-45 |
| | Cabling | Cat5e (or better) up to 100m |
| | Controller | Intel® Ethernet I350 Controller |
| | Network Transfer Rates Supported | 1GbE, 100MbE, 10MbE |
| | Data Path Width | PCIe Gen2.1x4 |
| | Power Requirement | 4.4W (typical) |
| | Operating Temperature | 32° to 131° F (0° to 55° C) |
| | Dimensions (HxW) | 2.75 x 5.5 inches (without brackets) |
| | Operating System Driver Support | Windows 10 64-bit Linux® |
| | Kit Contents | <ul style="list-style-type: none">• Intel® I350-T2 2-Port 1GbE NIC with standard height bracket attached• Low-profile bracket• Product Literature |

| | | |
|---------------------------------------|---|---|
| Intel® I350-T4 4-Port 1GbE NIC | Connector | 4 RJ-45 |
| | Cabling | Cat5e (or better) up to 100m |
| | Controller | Intel® Ethernet I350 Controller |
| | Network Transfer Rates Supported | 1GbE, 100MbE, 10MbE |
| | Data Path Width | PCIe Gen2.1x4 |
| | Power Requirement | 5W (typical) |
| | Operating Temperature | 32° to 131° F (0° to 55° C) |
| | Dimensions (HxW) | 2.75 x 5.5 inches (without brackets) |
| | Operating System Driver Support | Windows 10 64-bit Linux® |
| | Kit Contents | <ul style="list-style-type: none">• Intel® I350-T4 4-Port 1GbE NIC with standard height bracket attached• Low-profile bracket• Product Literature |

Technical Specifications - Networking and Communications

| | | |
|---|---|---|
| Intel® I225-T1 1-Port 2.5GbE NIC *Planned to be available in Q3,2021 | Connector | 1 RJ-45 |
| | Cabling | Cat5e (or better) up to 85m |
| | Controller | Intel® Ethernet I225 Controller |
| | Network Transfer Rates Supported | 2.5GbE, 1GbE, 100MbE, 10MbE |
| | Data Path Width | PCIe Gen3.1x1 |
| | Power Requirement | 2W (typical) |
| | Operating Temperature | 32° to 158° F (0°C to 70°C) |
| | Operating System Driver Support | Windows 10 64-bit Linux® |
| | Kit Contents | <ul style="list-style-type: none"> • Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached • Low-profile bracket • Product Literature |

| | | |
|---|------------------------------|--|
| Intel® Wi-Fi 6 AX201 802.11ax, BT 5.1, M.2 | WLAN Standards | 802.11-2016 and select amendments (selected feature coverage) 802.11 a,b,d,e,g,h,i,k,n,r,u,v,w,ac,ax; Fine Measurment based on 802.11-2016 |
| | Antenna | 2x2 Dual-Band |
| | Bluetooth Standards | 5.1 |
| | Operating Temperature | 32° to 176° F (0° to 80° C) |
| | Interface | M.2 CNVio2 |
| | Dimensions | M.2 2230 |
| | Kit Contents | Not Available |

NOTE: Wireless access point and internet service required and sold separately. Availability of public wireless points limited. Wi-Fi 5 (802.11 ax) is backwards compatible with prior 802.11 specs.

Technical Specifications - Other Hardware

| | | |
|--|--|---------|
| Z2 G8 Tower Bezel w/ Dust Filter option | Part Number | 141L3AA |
| Overview | <p>Workstations are deployed in a variety of different ways and in different environments, from under a desk to manufacturing floors. HP Workstations designed a dust filter option to further protect the system against the ingress of dust and other particles over the life of the system. Tests have shown a reduction of dust ingress of up to 32% for the HP Z2 Tower G8 Workstation platform and is cleanable and serviceable by customers. There is also a BIOS setting that will warn customers when it is time to check and clean their filters.</p> | |
| Cleaning and servicing the dust filter | <p>After removing the filter from the system bezel (dust filter can be removed with the use of tools from the front bezel), either blow it with and wash with water or use a delicate duster (feather duster) to brush off the filter then rinse it with water.</p> <ol style="list-style-type: none"> Allow the filter half a day to dry at room temperature (25C at 30%-50% humidity). Temperature of water can be 0-70C, due to the dust filter meeting the SQTM 70C humidity test. Suggested water temperature for best user experience is 0-50C. Normal tap water (and most other types of water) can be used to rinse the filter. Any type of corrosive liquid is restricted. | |
| Enabling the Check Filter warning in the BIOS: | <p>Customers must enable the BIOS setting once they receive their filter.</p> <ol style="list-style-type: none"> To enable, do the following once you see the boot screen for your system: F10 > Advanced > Built-In Device Options > Dust Filter Select to enable the Dust Filter replacement reminder, which can be set for 15, 30, 60, 90, 120, or 180 days. The Reminder will show during POST after the reminder timer has expired. | |
| BIOS Warnings | <p>NOTE: customers who anticipate more dust ingress in their environments should set the reminder for a shorter window. Customers anticipating longer dust ingress can set the reminder for a longer window.</p> <p>Large enterprise customers deploying multiple systems can centrally enable/disable the BIOS warning using the WMI/BCU tool remotely to set the options below:</p> <p>Dust Filter</p> <ul style="list-style-type: none"> Disable* Enable <p>Dust Filter Reminder (Days) 15, 30, 60*, 90, 120, and 180</p> | |
| Z2 G8 Tower Dust Filter (Filter Only) | Part Number | 141L2AA |
| <p>This is intended to be a replacement filter for the HP Z2 Tower G8 Workstation in the event that the original filter would need to be replaced.</p> | | |

Technical Specifications - Other Hardware

| | | |
|--|--------------------|---------|
| HP Z2 Tower PCIe Card Holder/Blower Kit | Part Number | 2B1D4AA |
|--|--------------------|---------|

Features

This card holder/blower kit is required to enable added mechanical stability when configuring select graphics cards on the HP Z2 Tower G8 Workstation.

The kit enables added mechanical stability when configuring:

- 2x AMD Radeon™ Pro WX 3200 4GB
- 1x AMD Radeon™ Pro W5500 8GB
- 1x AMD Radeon™ Pro W5700 8GB
- 2x NVIDIA® Quadro® P400
- 2x NVIDIA® T1000 4GB
- 1x NVIDIA® RTX® A5000 24GB
- 1x NVIDIA® RTX® A4000 16GB

NOTE: If one of the above graphics cards is configured with the Z2 G8 TWR at time of purchase or the 700W chassis is configured, the Card Holder/Blower is automatically included.

- If one of the above graphics cards is added as an aftermarket option, the Card holder/Blower Kit (2B1D4AA) is required, as a separate purchase, for installation of the graphics card.
-

Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - o Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initial)
 - ✍ 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - ✍ 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - ✍ 2 red + 4 white BIOS recovery is in progress
 - ✍ 3 red + 2 white Memory could not be initialized
 - ✍ 3 red + 3 white Graphics adaptor could not be found
 - ✍ 3 red + 4 white Power supply failure / not connected
 - ✍ 3 red + 5 white Processor not installed
 - ✍ 3 red + 6 white Current processor does not support an enabled feature
 - ✍ 3 red + 7 white Computer cover has been removed since last system startup
 - ✍ 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - ✍ 4 red + 3 white System internal temperature has exceeded its threshold
 - ✍ 5 red + 2 white System controller firmware is not valid
 - ✍ 5 red + 3 white System controller detected BIOS is not executing
 - ✍ 5 red + 4 white BIOS could not complete initialization / PCA failure
 - ✍ 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - o This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software⁵ Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Blue Pull Tabs, and Quick Release Latches for easy Identification

Summary of Changes

| Date of change: | Version History: | | Description of change: |
|------------------------|-------------------------|---------|--|
| May 3, 2021 | From v1 to v2 | Changed | Format page 2 |
| May 13, 2021 | From v2 to v3 | Added | Intel Xeon W-1300 series |
| May 26, 2021 | From v3 to v4 | Changed | SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS and Social and Environmental Responsibility sections |
| June 11, 2021 | From v4 to v5 | Changed | Hard Drive Controllers section |

title

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